

# DATA SHEET

**ELECTROSTATIC DISCHARGE  
PROTECTION DEVICES**

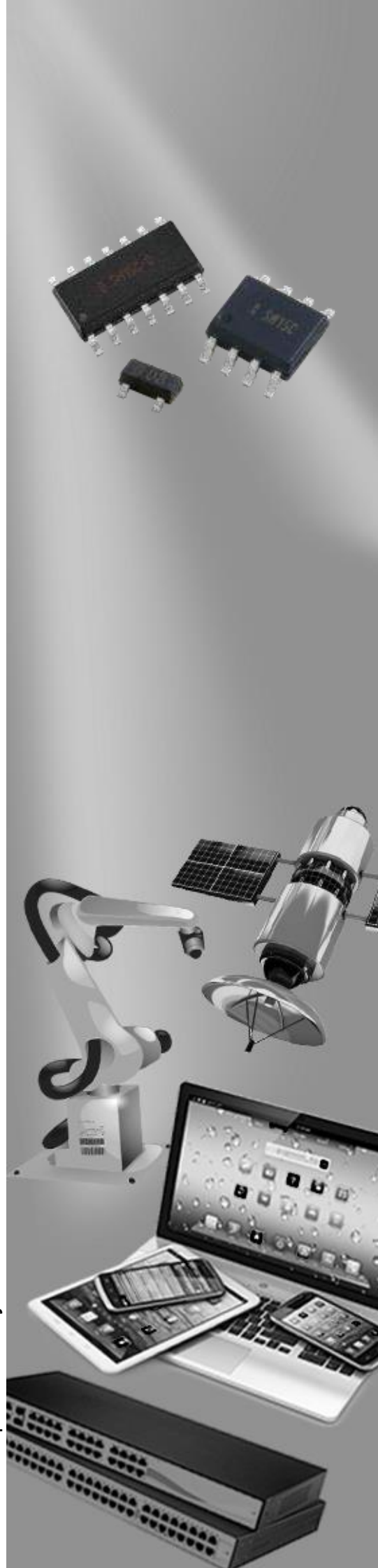
**INDUSTRIAL / CONSUMER**

SES08CXXL04 SERIES

RoHS compliant & Halogen free



Product specification—June 30, 2023 V.1



## Electrostatic Discharged Protection Devices (ESD) Data Sheet

### Description

Brightking's SES08CXXL04 series are designed to provide bi-directional protection for sensitive electronics from damage or latch-up due to ESD, lightning and other voltage-induced transient events. Each device will protect four data or I/O lines. It use to meet the immunity requirements of IEC61000 Level 4 (30KV air, 30KV contact discharge).

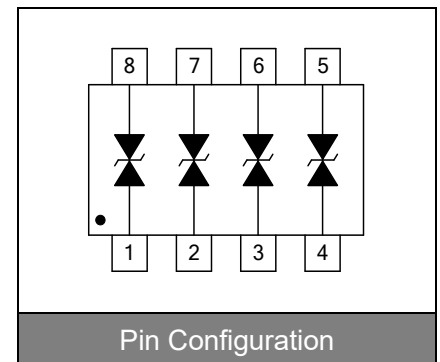


Contact :  $\pm 30\text{kV}$   
Air :  $\pm 30\text{kV}$



### Features

- IEC61000-4-2 ESD 30KV Air, 30KV contact compliance
- SOIC-08 surface mount package
- Protects four I/O lines
- Peak power dissipation of 500W under 8/20 $\mu\text{s}$  waveform
- Working voltage: 5V,12V,15V
- Low leakage current
- Low capacitance and clamping voltage
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270 $^{\circ}\text{C}$
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020



### Applications

- RS-232 and RS-422 data line protection
- Microprocessor based equipment
- Audio/Video input protection
- Notebooks, desktops, servers
- Wireless network systems
- Set Top Box (STB)
- Series and parallel ports
- Instrumentation
- Peripherals

### Maximum Ratings

| Rating  | Symbol         | Value    | Unit               |
|---|----------------|----------|--------------------|
| Peak pulse power (tp=8/20 $\mu\text{s}$ waveform) | $P_{PP}$       | 500      | W                  |
| ESD voltage (Contact discharge)                   | $V_{ESD}$      | $\pm 30$ | kV                 |
| ESD voltage (Air discharge)                       |                | $\pm 30$ |                    |
| Storage & operating temperature range             | $T_{STG}, T_J$ | -55~+150 | $^{\circ}\text{C}$ |

**Electrical Characteristics (T<sub>J</sub>=25°C)**

## SES08C05L04 (Marking: B SM05C)

| Parameter                      | Symbol           | Condition                                | Min. | Typ. | Max. | Unit |
|--------------------------------|------------------|--|------|------|------|------|
| Reverse stand-off voltage      | V <sub>RWM</sub> |  |      |      | 5    | V    |
| Reverse breakdown voltage      | V <sub>BR</sub>  | I <sub>BR</sub> =1mA                     | 6    |      |      | V    |
| Reverse leakage current        | I <sub>R</sub>   | V <sub>R</sub> =5V<br>Each I/O pin       |      |      | 20   | μA   |
| Clamping voltage (tp=8/20μs)   | V <sub>C</sub>   | I <sub>PP</sub> =1A                      |      |      | 9.8  | V    |
| Clamping voltage (tp=8/20μs)   | V <sub>C</sub>   | I <sub>PP</sub> =10A                     |      |      | 13.5 | V    |
| Peak Pulse Current(tp=8/20μs)  | I <sub>PP</sub>  |  |      |      | 10   | A    |
| Off state junction capacitance | C <sub>J</sub>   | 0Vdc, f=1MHz<br>Between I/O pins and GND |      | 300  |      | pF   |

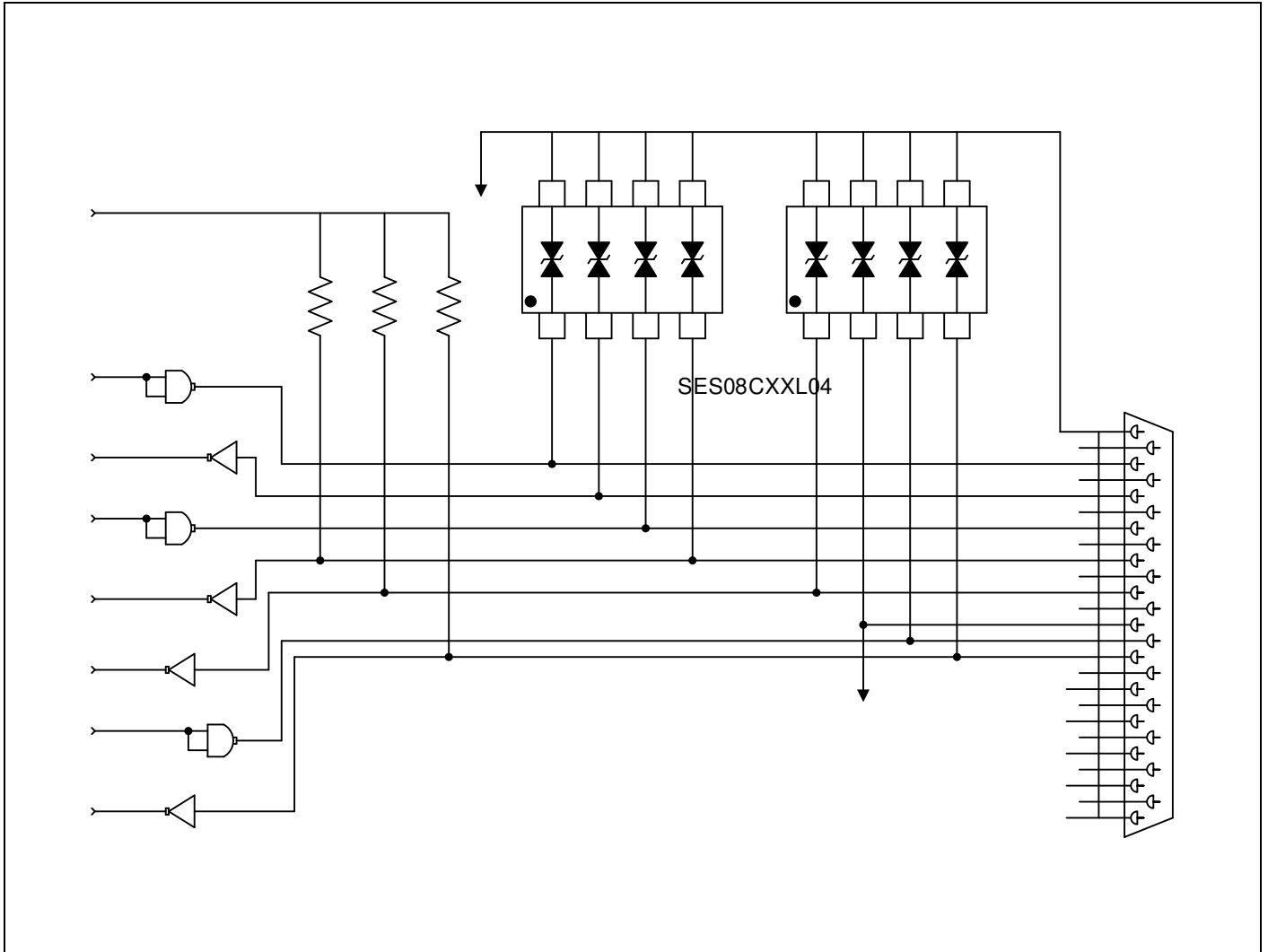
## SES08C12L04 (Marking: B SM12C)

| Parameter                      | Symbol           | Condition                                | Min. | Typ. | Max. | Unit |
|--------------------------------|------------------|--|------|------|------|------|
| Reverse stand-off voltage      | V <sub>RWM</sub> |  |      |      | 12   | V    |
| Reverse breakdown voltage      | V <sub>BR</sub>  | I <sub>BR</sub> =1mA                     | 13.3 |      |      | V    |
| Reverse leakage current        | I <sub>R</sub>   | V <sub>R</sub> =12V<br>Each I/O pin      |      |      | 1    | μA   |
| Clamping voltage (tp=8/20μs)   | V <sub>C</sub>   | I <sub>PP</sub> =1A                      |      |      | 21   | V    |
| Clamping voltage (tp=8/20μs)   | V <sub>C</sub>   | I <sub>PP</sub> =10A                     |      |      | 25.9 | V    |
| Peak Pulse Current(tp=8/20μs)  | I <sub>PP</sub>  |  |      |      | 10   | A    |
| Off state junction capacitance | C <sub>J</sub>   | 0Vdc, f=1MHz<br>Between I/O pins and GND |      | 100  |      | pF   |

## SES08C15L04 (Marking: B SM15C)

| Parameter                      | Symbol           | Condition                                | Min. | Typ. | Max. | Unit |
|--------------------------------|------------------|--|------|------|------|------|
| Reverse stand-off voltage      | V <sub>RWM</sub> |  |      |      | 15   | V    |
| Reverse breakdown voltage      | V <sub>BR</sub>  | I <sub>BR</sub> =1mA                     | 16.7 |      |      | V    |
| Reverse leakage current        | I <sub>R</sub>   | V <sub>R</sub> =15V<br>Each I/O pin      |      |      | 1    | μA   |
| Clamping voltage (tp=8/20μs)   | V <sub>C</sub>   | I <sub>PP</sub> =1A                      |      |      | 24   | V    |
| Clamping voltage (tp=8/20μs)   | V <sub>C</sub>   | I <sub>PP</sub> =12A                     |      |      | 30   | V    |
| Peak Pulse Current(tp=8/20μs)  | I <sub>PP</sub>  |  |      |      | 12   | A    |
| Off state junction capacitance | C <sub>J</sub>   | 0Vdc, f=1MHz<br>Between I/O pins and GND |      | 80   |      | pF   |

### Applications Information



### Typical Characteristics Curves

Figure 1. Power Derating Curve

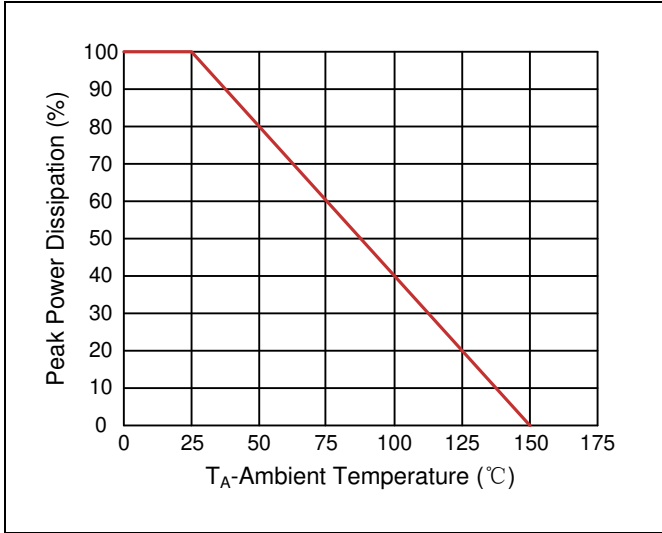


Figure 2. Pulse Waveforms

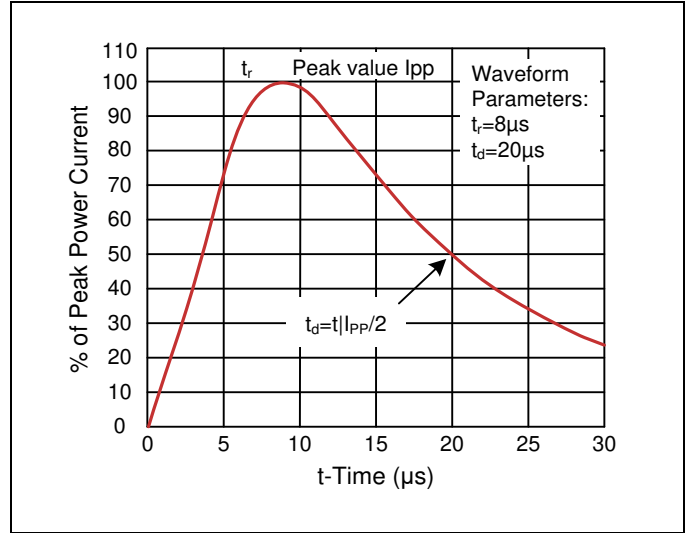
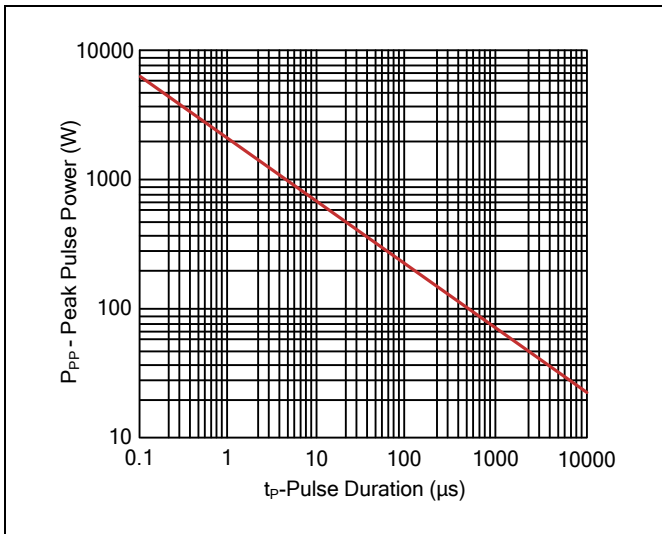
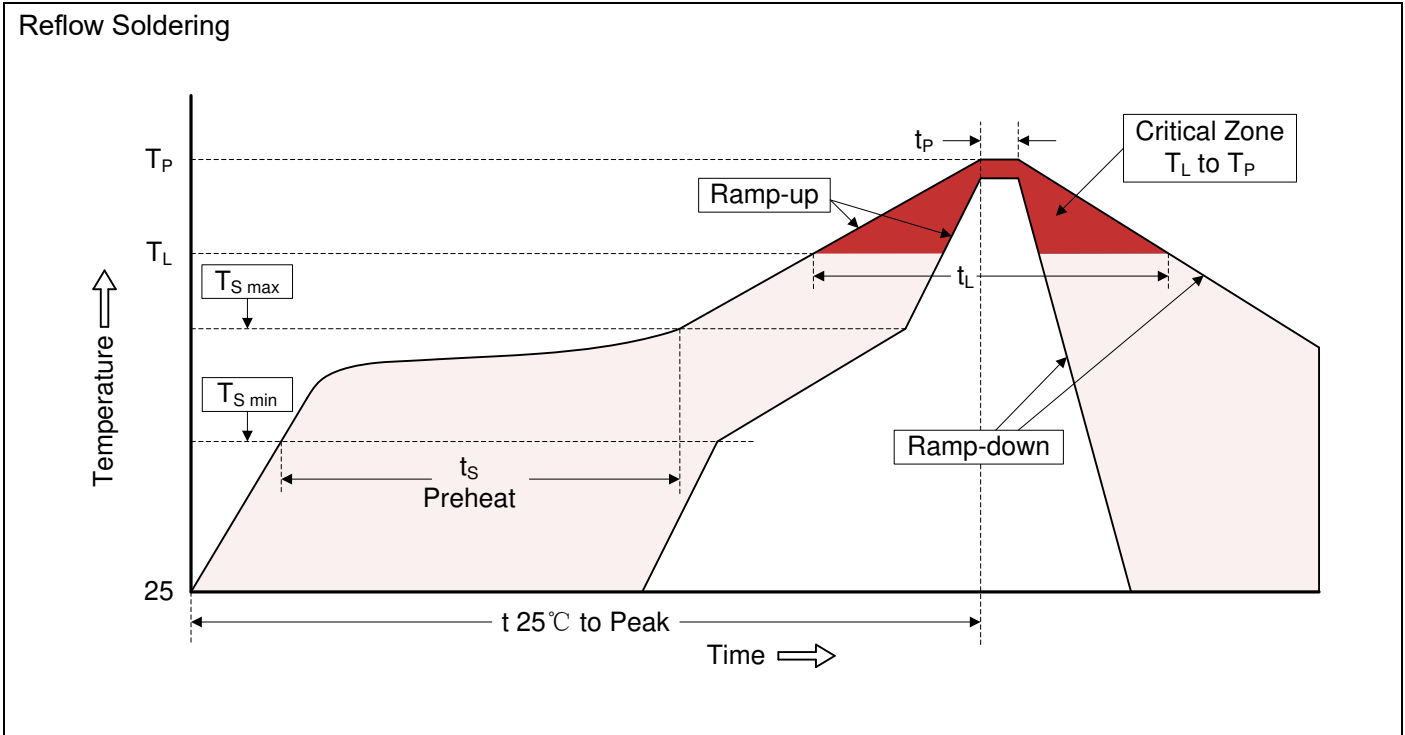


Figure 3. Non-Repetitive Peak Pulse vs. Pulse Time



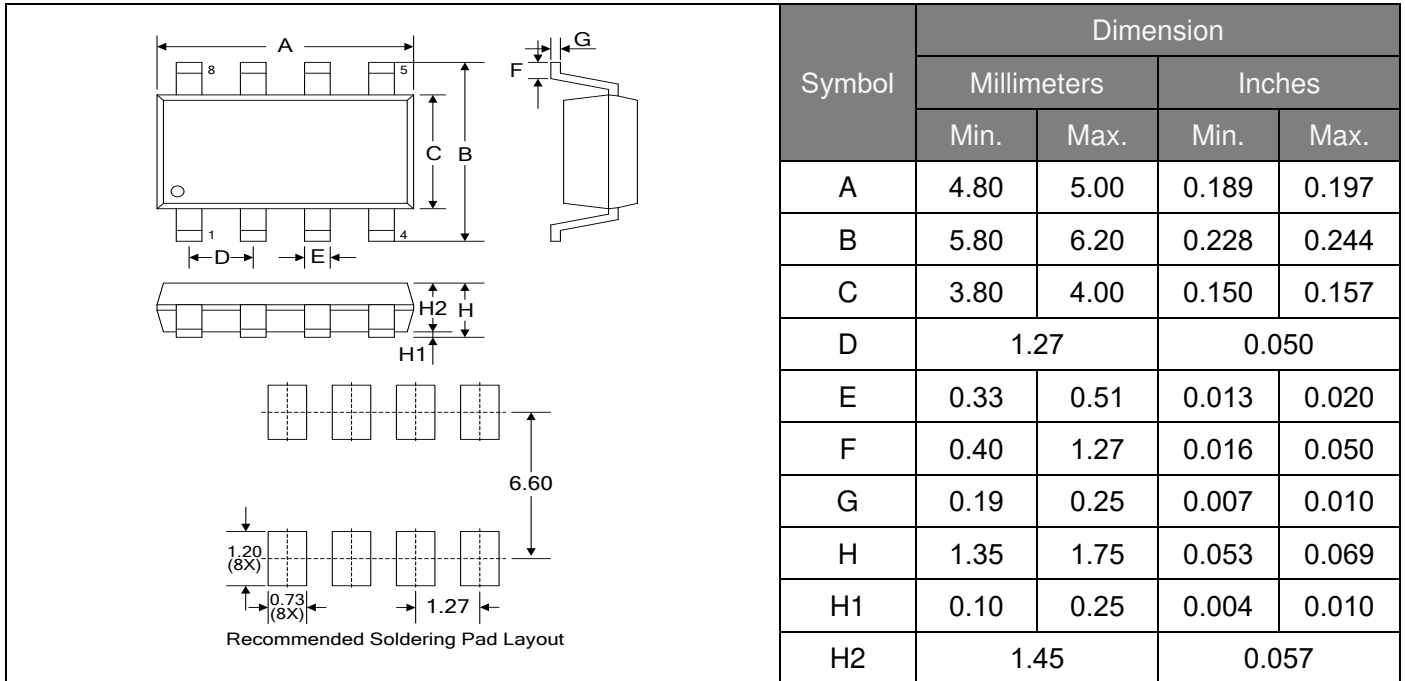
**Recommended Soldering Conditions**



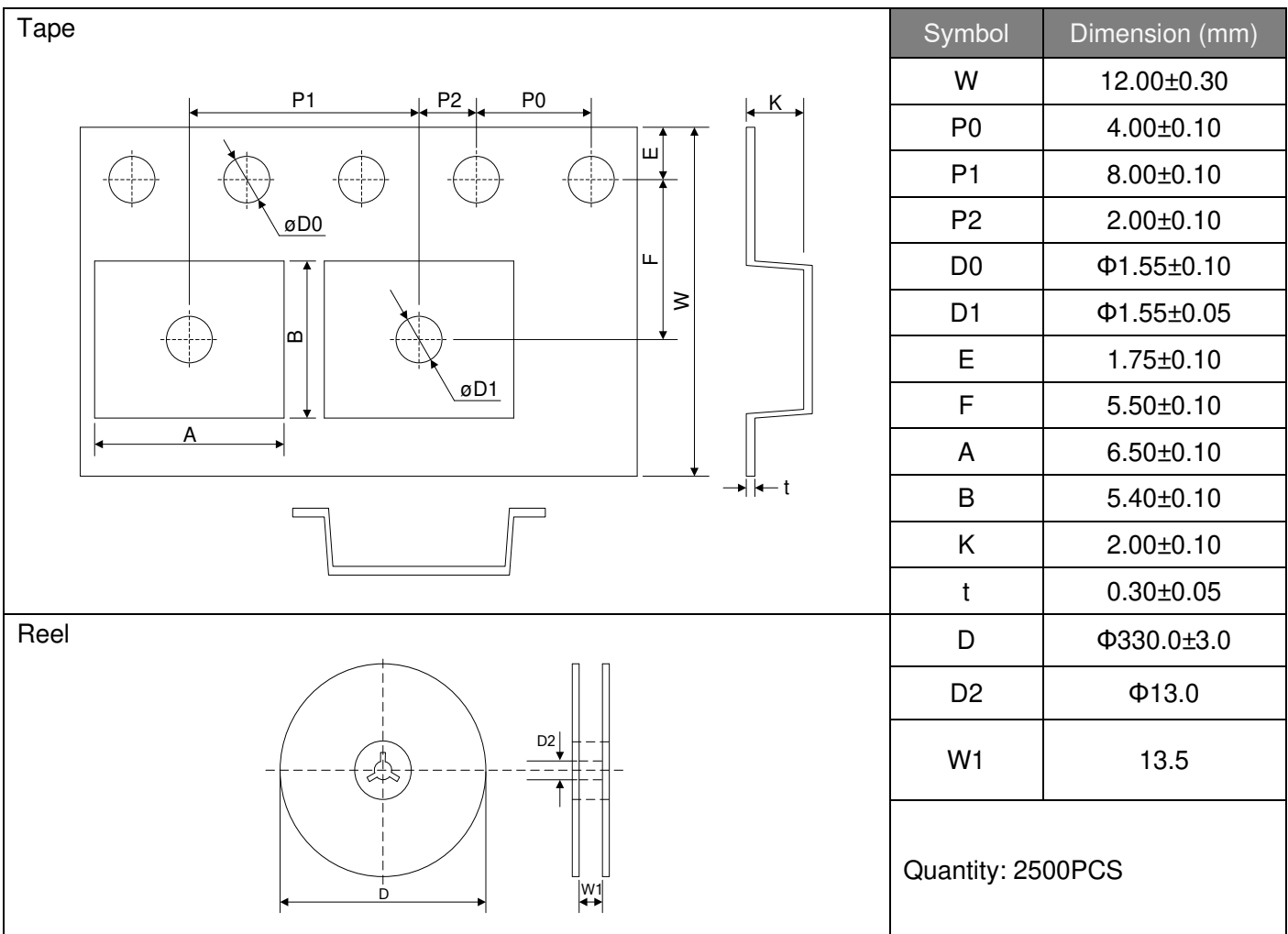
**Recommended Conditions**

| Profile Feature                                      | Pb-Free Assembly |
|--|------------------|
| Average ramp-up rate ( $T_L$ to $T_P$ )              | 3°C/second max.  |
| Preheat  | 150°C            |
| -Temperature Min ( $T_{S\ min}$ )                    | 200°C            |
| -Temperature Max ( $T_{S\ max}$ )                    | 60-180 seconds   |
| -Time (min to max) ( $t_s$ )                         | 3°C/second max.  |
| $T_{S\ max}$ to $T_L$                                |                  |
| -Ramp-up Rate  |                  |
| Time maintained above:                               | 217°C            |
| -Temperature ( $T_L$ )                               | 60-150 seconds   |
| -Time ( $t_L$ )                                      |                  |
| Peak Temperature ( $T_P$ )                           | 260°C            |
| Time within 5°C of actual Peak Temperature ( $t_P$ ) | 20-40 seconds    |
| Ramp-down Rate                                       | 6°C/second max.  |
| Time 25°C to Peak Temperature                        | 8 minutes max.   |

**Dimensions (SOIC-08)**



**Packaging**



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